

Initial Product/Process Change Notification Document #:IPCN23108X

Issue Date:08 Mar 2020

Title of Change:	Dual Source Qualificati	Dual Source Qualification for QFN 1.45x1.0 6L in UTAC, Thailand.		
Proposed First Ship date:	08 Sep 2020 or earlier if approved by customer			
Contact Information:	Contact your local ON Semiconductor Sales Office or < <u>CI.Fong@onsemi.com</u> >			
PCN Samples Contact:	Sample requests are to Initial PCN or Final PCN Samples delivery timin	Contact your local ON Semiconductor Sales Office or <pcn.samples@onsemi.com>. Sample requests are to be submitted no later than 30 days from the date of first notification, Initial PCN or Final PCN, for this change. Samples delivery timing will be subject to request date, sample quantity and special customer packing/label requirements.</pcn.samples@onsemi.com>		
Type of Notification:	advance notification a change details and d plan.The completed Product/Process Chan Product/Process Chan	This is an Initial Product/Process Change Notification (IPCN) sent to customers. An IPCN is an advance notification about an upcoming change and contains general information regarding the change details and devices affected. It also contains the preliminary reliability qualification plan. The completed qualification and characterization data will be included in the Final Product/Process Change Notification (FPCN). This IPCN notification will be followed by a Final Product/Process Change Notification (FPCN) at least 90 days prior to implementation of the change. In case of questions, contact <pcn. support@onsemi.com=""></pcn.>		
Marking of Parts/ Traceability of Change:	UTAC parts will have tracecode (line2) of Gxxxxx.			
Change Category:	Assembly Change, Tes	Assembly Change, Test Change		
Change Sub-Category(s):	Manufacturing Site Ad	Manufacturing Site Addition		
Sites Affected:				
ON Semiconductor Sites		External Foundry/Subcon Sites		
None		UTAC, Thailand		
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Description and Purpose:

This initial notification announces the intention to expand the assembly and final test capacity site for dual source of 4 OPNs

	Before Change Description	After Change Description	
Mold Compound	Mold Compound HITACHI CEL9220HF13H HF		SUMITOMO G770HCD
Wire Loop Profile	Reverse Bond	Reverse Bond	Forward Bond
Assembly & Final Test Site HANA		HANA	UTAC

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Qualification Plan:

QV DEVICE NAME: FSA4157AL6X

RMS : TBD

PACKAGE : QFN 1.45x1.0 6L

Test	Specification	Condition	Interval
HTOL	JESD22-A108	TA=125C, bias at 1.2X Nominal	1008 hours
HTSL	JESD22-A103	Temp =150C	1008 hours
HAST	JESD22-A110	Temp = 130C, 85% RH, ~ 18.8 psig, bias = 100% of rated V or 100V max	96 hours
TC	JESD22-A104	Temp = -65°C to +150°C	500 cyc
uHAST	JESD22-A118	Temp = 130C, RH=85%, ~18.8 psig	96 hours

Estimated date for qualification completion: 8 May 2020

List of Affected Parts:

Note: Only the standard (off the shelf) part numbers are listed in the parts list. Any custom parts affected by this PCN are shown in the customer specific PCN addendum in the PCN email notification, or on the <u>PCN Customized Portal</u>.

Part Number	Qualification Vehicle
FAN156L6X	FSA4157AL6X
FSA4157AL6X	FSA4157AL6X
FSA4159L6X	FSA4157AL6X
FSA1156L6X	FSA4157AL6X

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Appendix A: Changed Products

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Product	Customer Part Number	Qualification Vehicle	New Part Number	Replacement Supplier
FSA1156L6X		FSA4157AL6X		
FSA4159L6X		FSA4157AL6X		
FSA4157AL6X		FSA4157AL6X		
FAN156L6X		FSA4157AL6X		